Keep EN > VIN > GND

Do not float ENABLE

GND

Don't set R3 > 1 Ohm

R7, R8, R16 to adjust Fsw

1.85A rms

31.0V @ 1.3A

Vin 46V to 50V

Design Notes
1) R20 for test purposes only
2) optimize snubber R15, C12 on final layout
3) built on PCB PMP8668RevA

Revision History

Revision Notes

A *** preliminary ***

B HS gate resistor / loop

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